ASSOCIATION CONNECTING LECTRONICS INDUSTRIES	PC. Bannockl	burn. Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declara he declaration	ion of the s encompasse	ubstances es all lowe	within the 1 r level mate	manufacture rials for wh	er listed iten hich the man	n. Note: i ufacturer	f the item is an as has engineering	sembly with lower responsibility.
				Form Type Distribute	*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and					lls and Mfg	Informati	on	
Supplier Information														
Company name* Com			Company unique ID			Unique ID Authority					Response Date*			
onsemi											2023-06-12			
Contact Name Title - Contact					Phone - Contact*						Email - Contact*			
Product-Env-Stewards Product Envir			viro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative			esentative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product I			duct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Dat	e Version	]	Manufacturing Site		We	ight*	UOM	Unit Type
	NCP811	NCP81158MNTXG VR12.5 MOSF		T DRIVER		2023-06-12		1	TH6		29.	52	mg	Each
Manufacturing Proccess Informa	tion							·						
Terminal Plating / Grid Array Ma	Ferminal Plating / Grid Array Material Terminal Base Alloy			J-STD-020 MSI	L Rating Peak Process Body Temperature Max Time at Pea					ne at Peak T	k Temperature Number of Reflow Cycles			
Matte Tin (Sn) - annealed CU Alloy				1		260		С	30		seconds	3		
Comments														
evel 1 - maximum time at peak temperatu	re during so	Idering is 10-3	0 seconds											
for more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth					
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the				
Supplier Digital Signature Ra	stislav Drska	Le							

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.3	mg	Supplier	Silicon (Si)	7440-21-3		0.3	mg	
Die Attach	0.79	mg	Supplier	Silver (Ag)	7440-22-4		0.5925	mg	
			Supplier	Epoxy resins	129915-35-1		0.1975	mg	
Lead Frame	12.41	mg	Supplier	Silver (Ag)	7440-22-4		2.4448	mg	
			Supplier	Zinc (Zn)	7440-66-6		0.0124	mg	
			Supplier	Iron (Fe)	7439-89-6		0.1861	mg	
			Supplier	Copper (Cu)	7440-50-8		9.7667	mg	
Mold Compound-Black	15.0	mg		Epoxy resin	proprietary data		1.05	mg	
			Supplier	Phenolic Resin	Proprietary Data		1.05	mg	
			Supplier	Silica Amorphous (SiO2)	7631-86-9		2.25	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.075	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		10.575	mg	
Plating	0.6	mg	Supplier	Tin (Sn)	7440-31-5		0.6	mg	
Wire Bond - Cu	0.42	mg	Supplier	Copper (Cu)	7440-50-8		0.42	mg	

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3